

FEATURES

- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Designed to Comply With JEDEC 168-Pin and 200-Pin SDRAM Buffered DIMM Specification
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

DESCRIPTION

This 16-bit universal bus driver is designed for 1.65-V to 3.6-V V_{CC} operation.

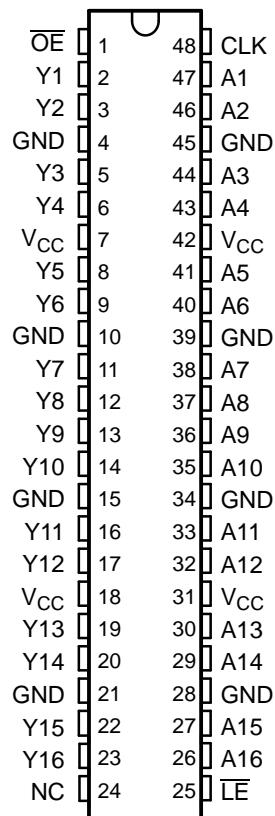
Data flow from A to Y is controlled by the output-enable (\overline{OE}) input. The device operates in the transparent mode when the latch-enable (\overline{LE}) input is low. When \overline{LE} is high, the A data is latched if the clock (CLK) input is held at a high or low logic level. If \overline{LE} is high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16334 is characterized for operation from -40°C to 85°C.

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

INPUTS				OUTPUT Y
\overline{OE}	\overline{LE}	CLK	A	
H	X	X	X	Z
L	L	X	L	L
L	L	X	H	H
L	H	↑	L	L
L	H	↑	H	H
L	H	L or H	X	$Y_0^{(1)}$

(1) Output level before the indicated steady-state input conditions were established



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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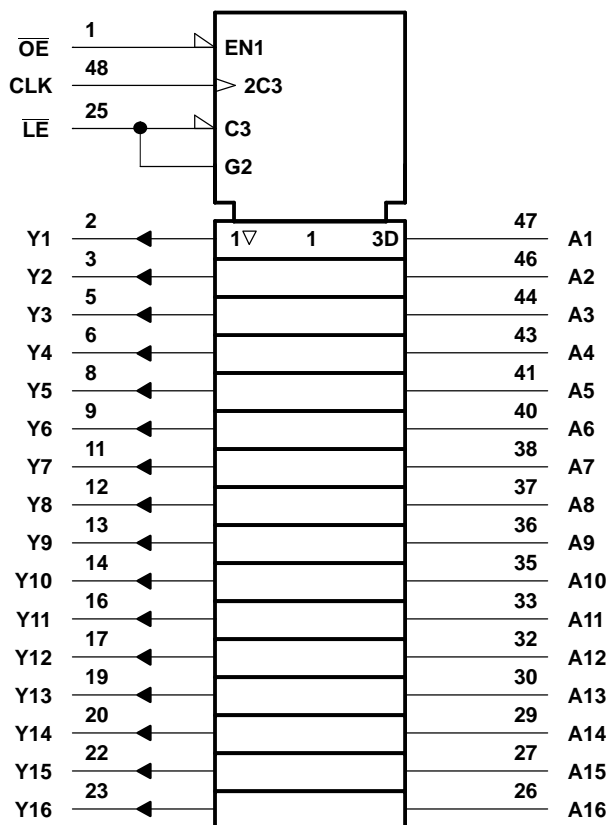
SN74ALVCH16334

16-BIT UNIVERSAL BUS DRIVER

WITH 3-STATE OUTPUTS

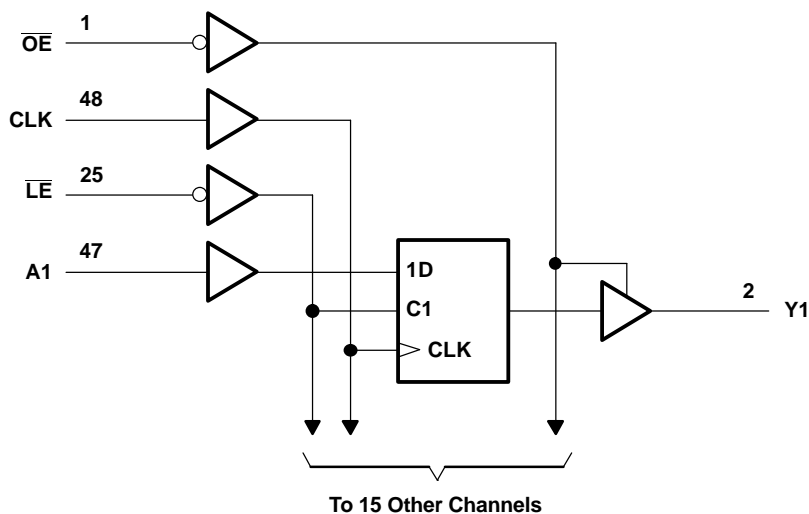
SCES090I—OCTOBER 1996—REVISED SEPTEMBER 2004

LOGIC SYMBOL⁽¹⁾



(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

LOGIC DIAGRAM (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	4.6	V
V_I	Input voltage range ⁽²⁾		-0.5	4.6	V
V_O	Output voltage range ⁽²⁾⁽³⁾		-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		-50	mA
I_{OK}	Output clamp current	$V_O < 0$		-50	mA
I_O	Continuous output current			±50	mA
	Continuous current through each V_{CC} or GND			±100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGG package		89	°C/W
		DGV package		93	
		DL package		94	
T_{stg}	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51.

SN74ALVCH16334
16-BIT UNIVERSAL BUS DRIVER
WITH 3-STATE OUTPUTS

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RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage		1.65	3.6	V
V_{IH}	High-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$		V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7		
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2		
V_{IL}	Low-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.35 \times V_{CC}$		V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.7		
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	0.8		
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 1.65\text{ V}$		-4	mA
		$V_{CC} = 2.3\text{ V}$		-12	
		$V_{CC} = 2.7\text{ V}$		-12	
		$V_{CC} = 3\text{ V}$		-24	
I_{OL}	Low-level output current	$V_{CC} = 1.65\text{ V}$		4	mA
		$V_{CC} = 2.3\text{ V}$		12	
		$V_{CC} = 2.7\text{ V}$		12	
		$V_{CC} = 3\text{ V}$		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T_A	Operating free-air temperature		-40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}		I _{OH} = -100 µA	1.65 V to 3.6 V	V _{CC} - 0.2			V
		I _{OH} = -4 mA	1.65 V	1.2			
		I _{OH} = -6 mA	2.3 V	2			
		I _{OH} = -12 mA	2.3 V	1.7			
			2.7 V	2.2			
			3 V	2.4			
		I _{OH} = -24 mA	3 V	2			
V _{OL}		I _{OL} = 100 µA	1.65 V to 3.6 V			0.2	V
		I _{OL} = 4 mA	1.65 V			0.45	
		I _{OL} = 6 mA	2.3 V			0.4	
		I _{OL} = 12 mA	2.3 V			0.7	
			2.7 V			0.4	
		I _{OL} = 24 mA	3 V			0.55	
I _I		V _I = V _{CC} or GND	3.6 V			±5	µA
I _{I(hold)}		V _I = 0.58 V	1.65 V	25			µA
		V _I = 1.07 V	1.65 V	-25			
		V _I = 0.7 V	2.3 V	45			
		V _I = 1.7 V	2.3 V	-45			
		V _I = 0.8 V	3 V	75			
		V _I = 2 V	3 V	-75			
		V _I = 0 to 3.6 V ⁽²⁾	3.6 V			±500	
I _{OZ}		V _O = V _{CC} or GND	3.6 V			±10	µA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	3.6 V			40	µA
ΔI _{CC}		One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	µA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V	5.5			pF
	Data inputs			6			
C _o	Outputs	V _O = V _{CC} or GND	3.3 V	8			pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

			V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		(1)		150		150		150		MHz
t _w	Pulse duration	\overline{LE} low	(1)		3.3		3.3		3.3		ns
		CLK high or low	(1)		3.3		3.3		3.3		
t _{su}	Setup time	Data before CLK↑	(1)		1.4		1.7		1.5		ns
		Data before \overline{LE} ↑	(1)		1.2		1.6		1.3		
			(1)		1.4		1.5		1.2		
t _h	Hold time	Data after CLK↑	(1)		0.9		0.8		0.9		ns
		Data after \overline{LE} ↑	(1)		1.2		1.1		1.1		

(1) This information was not available at the time of publication.

SN74ALVCH16334

16-BIT UNIVERSAL BUS DRIVER WITH 3-STATE OUTPUTS

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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f_{\max}			(1)		150		150		150		MHz
t_{pd}	A	Y	(1)		1	3.7	3.6		1.1	3.3	ns
	\overline{LE}		(1)		1	4.8	5		1.3	4.4	
	CLK		(1)		1	4.4	4.5		1	4.1	
t_{en}	\overline{OE}	Y	(1)		1	5.4	5.4		1.1	4.6	ns
t_{dis}	\overline{OE}	Y	(1)		1	4.1	4.5		1.7	4.4	ns

(1) This information was not available at the time of publication.

OPERATING CHARACTERISTICS

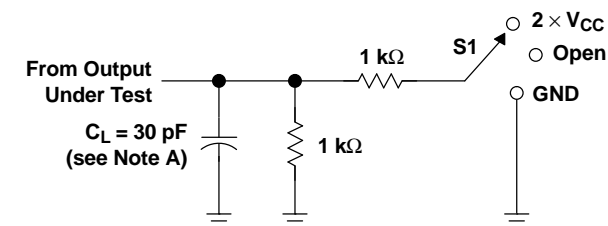
$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
			TYP	TYP	TYP	
C_{pd} Power dissipation capacitance	Outputs enabled	$C_L = 0$, $f = 10\text{ MHz}$	(1)	32	37	pF
	Outputs disabled		(1)	7	11	

(1) This information was not available at the time of publication.

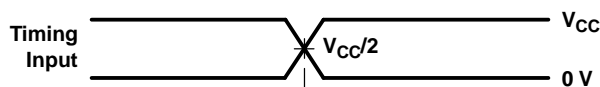
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 1.8 \text{ V}$

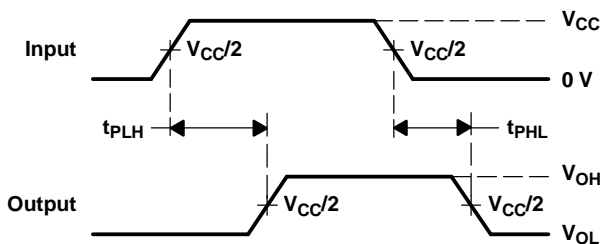


LOAD CIRCUIT

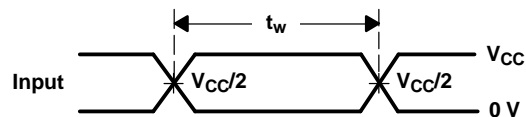
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



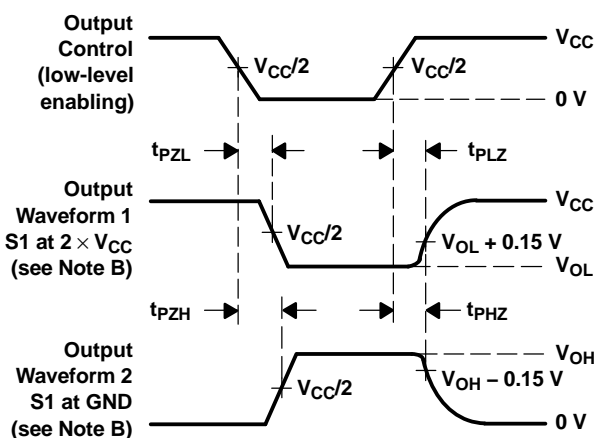
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



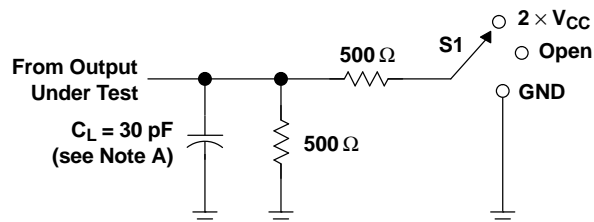
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

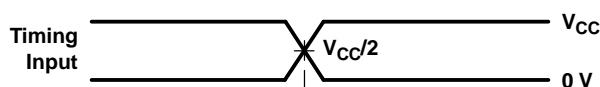
PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$

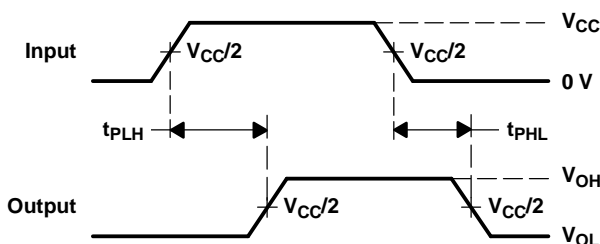


LOAD CIRCUIT

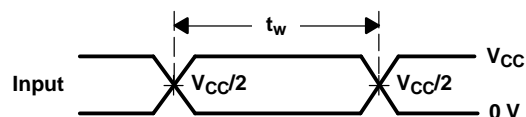
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



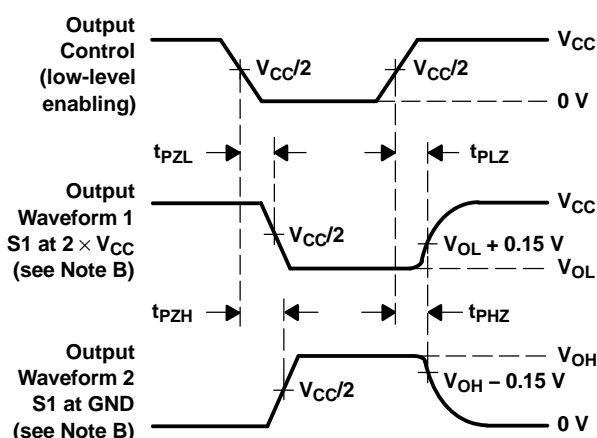
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



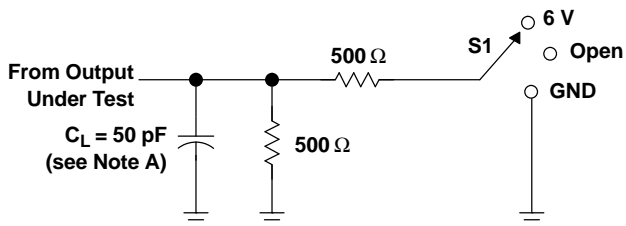
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ENABLE AND DISABLE TIMES

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 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

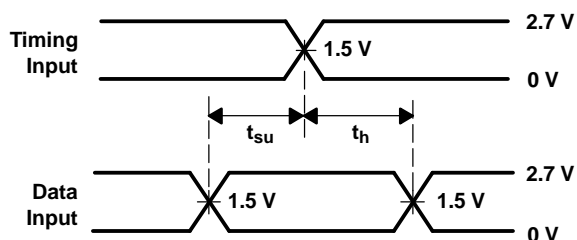
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.7\text{ V}$ AND $3.3\text{ V} \pm 0.3\text{ V}$

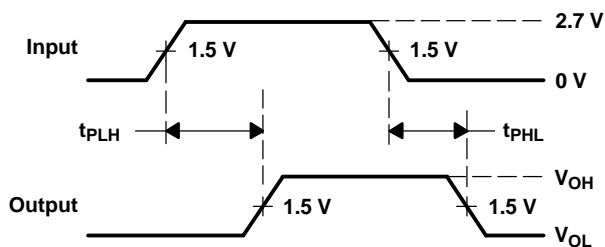


LOAD CIRCUIT

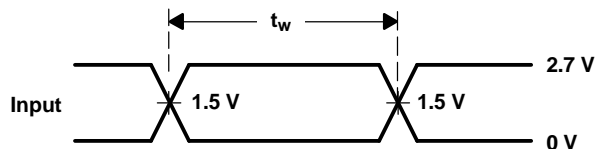
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



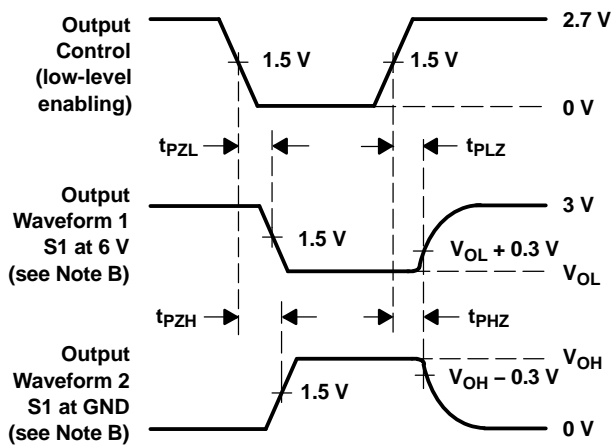
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALVCH16334DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16334	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

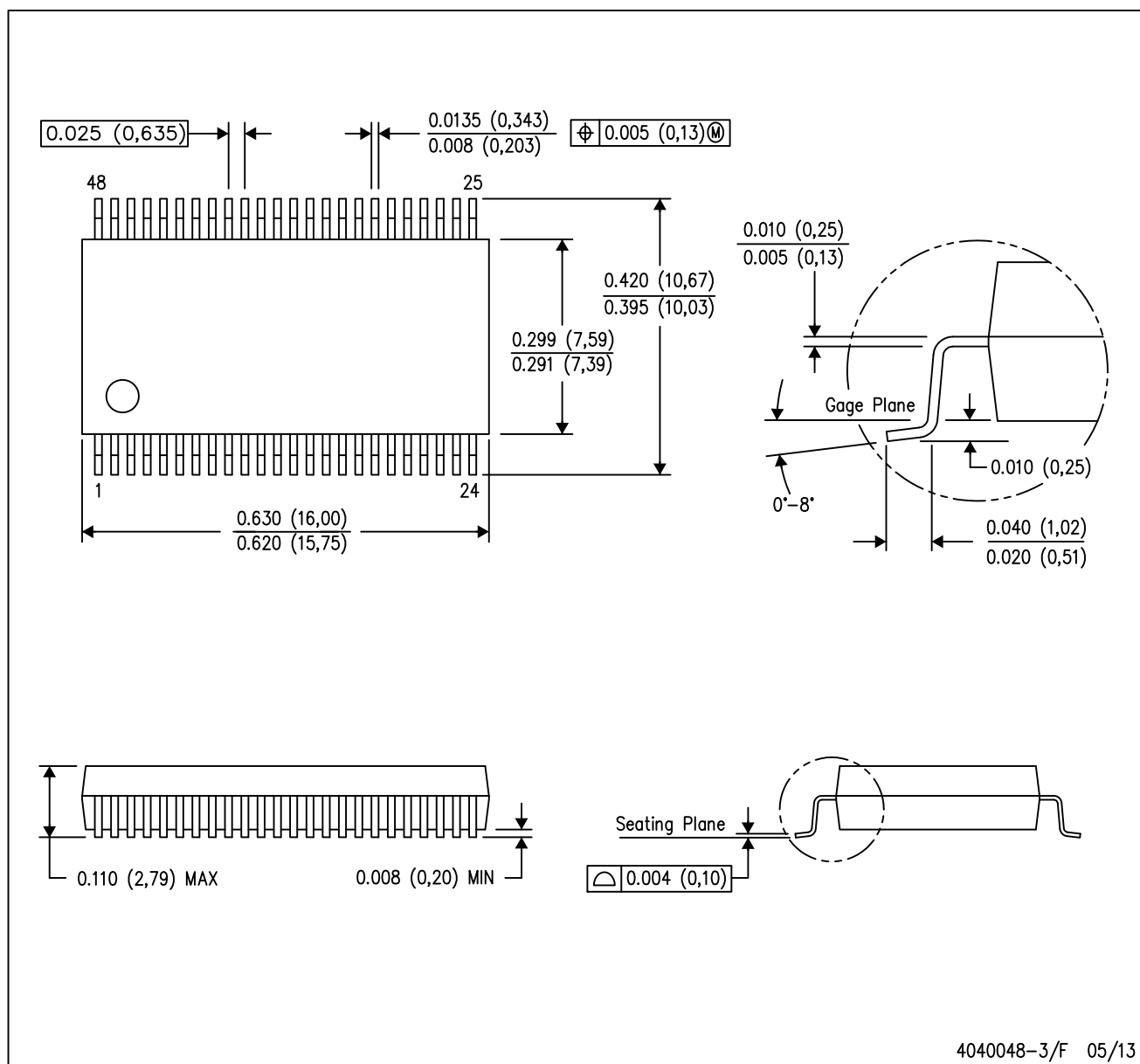
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MO-118

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